DTU Danchip National Center for Micro- and Nanofabrication	Process flow title **AZ MiR 701 on Si**			Revision **1.1**
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	Labmanager group Lithography	Batch name Litho TPT first print	Date of creation 20160314	Date of revision 20160405

Objective

Batch name: Litho TPT first print

This process flows is a guideline on how to prime, spin coat, expose, develop, and inspect 1.5 µm AZ MiR 701 on Si substrates using Spin Coater: Gamma UV, Aligner: MA6-2 / KS Aligner, and Developer: TMAH UV-lithography.

Step Header		Equipment		Comments
1	**Spin coating of AZ MiR 701 with HMDS priming**			
1.1	Coat wafers	Spin Coater: Gamma UV	**Resist:** AZ MiR 701 29cps (Resist 1) **HMDS priming:** 15 s @ 120°C (contact angle ~70°) **Spin:** 30 s @ 4600 rpm (~1.5 µm) **Softbake:** 60 s @ 90 °C (1 mm proximity) **Sequence:** (1411) DCH 100mm MiR 701 1.5um HMDS	Substrates: New Si
2	**UV Exposure**			
2.1	Exposure	Aligner: MA6 – 2 or KS Aligner	**Mask:** Litho test **Exposure mode:** Hard contact HC wait time: 10 s **Exposure dose:** 189 mJ/cm^2 for MA6 – 2 169 mJ/cm^2 for KS	Exposure time: 14.5s @ 13mW/cm^2 for MA6-2 24s @ 7mW/cm^2 for KS
3	**Development with PEB**			
3.1	Development	Developer: TMAH UV-lithography	**Post Exposure Bake:** 60 s @ 110°C **Development in AZ 726 MIF:** single puddle, 60 s **Sequence:** (3001) DCH 100mm PEB60s@110C+SP60s	PEB and development is done sequentially
4	**Inspection**			
4.1	Inspection	Optical microscope	**Inspect:** Line and dot patterns, bright field and dark field (possibly also alignment squares north of these)